

**ABSTRACT OF THE DISCLOSURE**

5 A fabrication method of wafer level packages  
capable of improving reliability by maximizing a contact area  
of metal wiring and a conductive ball and of simplifying  
fabrication processes by reducing the number of sputtering.  
The disclosed method comprises the steps of: providing a  
substrate having a plurality of chip pads on the upper part  
10 thereof; forming a first insulating layer including a first  
opening exposing the chip pad and a second opening forming a  
ball land on the substrate; forming metal wiring connected to  
the chip pad in a single unit through the first opening and  
covering the second opening to have a ball land on the first  
15 insulating layer; forming a second insulating layer including  
a third opening which covers the metal wiring, however,  
exposes the ball land; and adhering a conductive ball to be  
in contact with the third opening on the ball land.